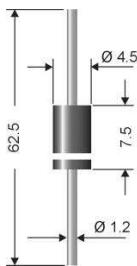


BY 3060



Type	Repetitive peak reverse voltage V_{RRM} V	Surge peak reverse voltage V_{RSM} V	Max. reverse recovery time $I_F = -A$ $I_R = -A$ $I_{RR} = -A$ t_{rr} ns	Max. forward voltage $V_F^{2)}$
BY 3060	600	700	-	1,1

Axial lead diode

Standard silicon rectifier diodes

BY 3060

Forward Current: 3 A

Reverse Voltage: 600 to 600 V

Features

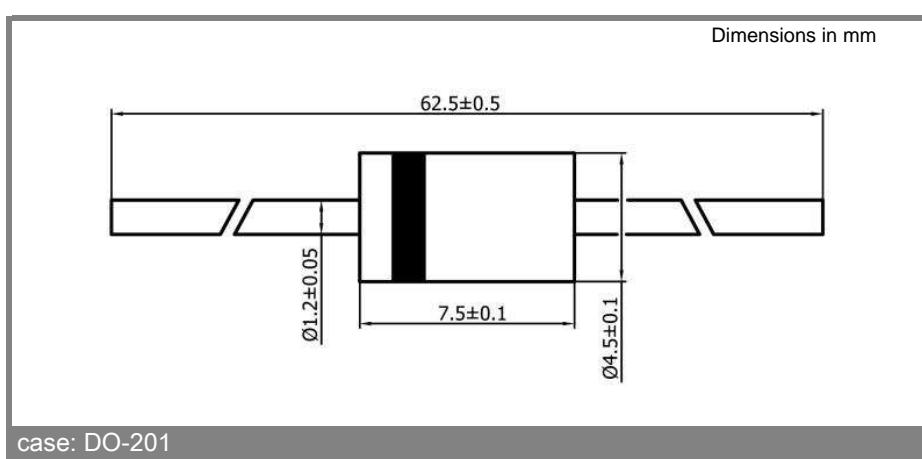
- Max. solder temperature: 260°C
- Plastic material has UL classification 94V-0

Mechanical Data

- Plastic case DO-201
- Weight approx.: 1 g
- Terminals: plated terminals solderable per MIL-STD-750
- Mounting position: any
- Standard packaging: 1700 pieces per ammo

Absolute Maximum Ratings		$T_c = 25^\circ\text{C}$, unless otherwise specified	
Symbol	Conditions	Values	Units
I_{FAV}	Max. averaged fwd. current, R-load, $T_A = 50^\circ\text{C}$ ¹⁾	3	A
I_{FRM}	Repetitive peak forward current $f > 15 \text{ Hz}^1)$	50	A
I_{FSM}	Peak forward surge current 50 Hz half sinus-wave ³⁾	250	A
i^2t	Rating for fusing, $t < 10 \text{ ms}^3)$	310	A^2s
R_{thA}	Max. thermal resistance junction to ambient ¹⁾	25	K/W
R_{thT}	Max. thermal resistance junction to terminals ¹⁾	-	K/W
T_j	Operating junction temperature	-50...+150	$^\circ\text{C}$
T_s	Storage temperature	-50...+175	$^\circ\text{C}$

Characteristics		$T_c = 25^\circ\text{C}$, unless otherwise specified	
Symbol	Conditions	Values	Units
I_R	Maximum leakage current, $T_j = 25^\circ\text{C}$; $V_R = V_{RRM}$	<10	μA
	$T_j = 25^\circ\text{C}$; $V_R = V_{RRM}$		
C_J	Typical junction capacitance (at MHz and applied reverse voltage of V)	-	pF
Q_{rr}	Reverse recovery charge ($U_R = V$; $I_F = A$; $dI_F/dt = A/\text{ms}$)	-	μC
E_{RSM}	Non repetitive peak reverse avalanche energy ($I_R = mA$; $T_j = 25^\circ\text{C}$; inductive load switched off)	-	mJ



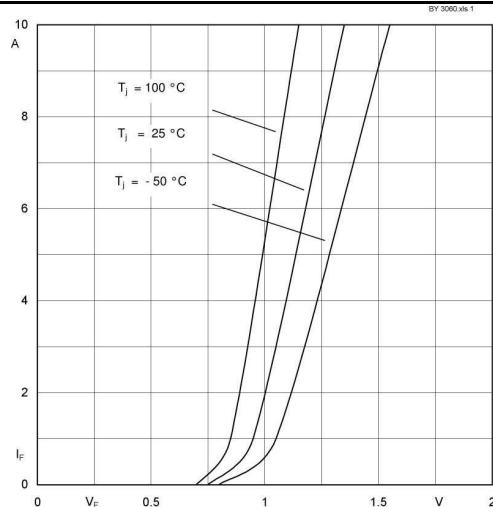


Fig. 1 Forward characteristic (typical values)

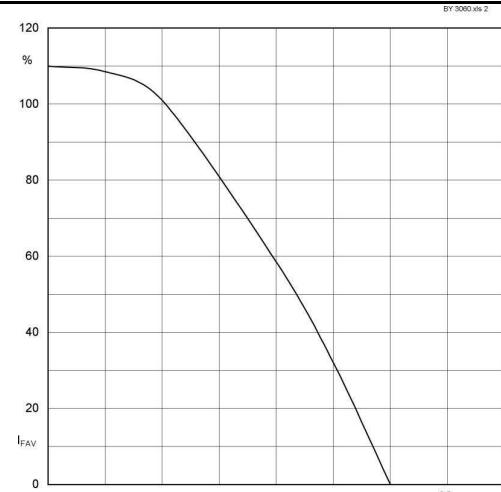


Fig. 2 Rated forward current vs. ambient temperature ¹⁾

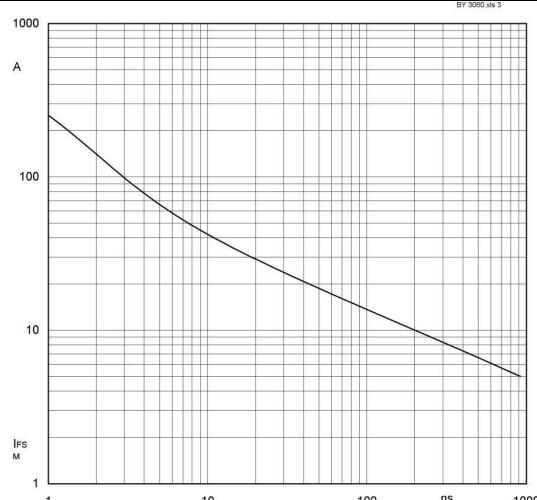


Fig. 3 I_{FS} current versus number of cycles at 50 Hz